

## Features

- Reliable and Rugged
- Green device available

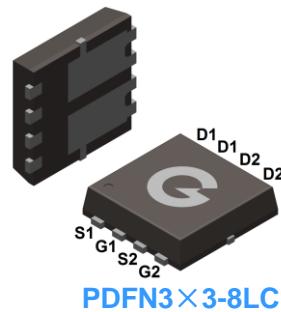
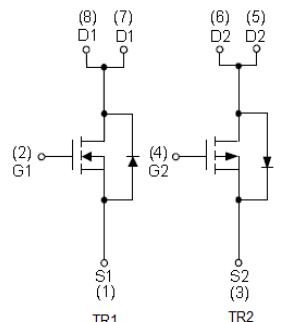
**HF**

## Applications

- Synchronous Rectification
- Motor Control
- Portable equipment application

## Mechanical Data

- Case: PDFN3x3-8LC
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208


**PDFN3×3-8LC**

## Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
GBLH3301-3DL8	PDFN3x3-8LC	5000 pcs / Tape & Reel	GBLH3301

## Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	TR1	TR2	Unit
Drain-to-Source Voltage	$V_{DSS}$	30	-30	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current ( $T_c = 25^\circ\text{C}$ ) <sup>*4</sup>	$I_D$	11	-13.3	A
Continuous Drain Current ( $T_c = 100^\circ\text{C}$ ) <sup>*4</sup>		7	-8.4	A
Pulsed Drain Current ( $T_c = 25^\circ\text{C}$ ) <sup>*1</sup>	$I_{DM}$	44	-53	A
Diode Continuous Forward Current( $T_c = 25^\circ\text{C}$ )	$I_S$	5.5	-6.6	A
Single Pulse Avalanche Energy <sup>*3</sup>	$E_{AS}$	7.3	20	mJ

## Thermal Characteristics

Parameter	Symbol	TR1	TR2	Unit
Power Dissipation ( $T_c = 25^\circ\text{C}$ )	$P_D$	6.25	10.4	W
Thermal Resistance Junction-to-Air <sup>*2</sup>	$R_{\theta JA}$	100	100	°C/W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	20	12	°C/W
Operating Junction Temperature Range	$T_J$	-55 ~ +150		°C
Storage Temperature Range	$T_{STG}$	-55 ~ +150		°C

**Electrical Characteristics-TR1** (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu\text{A}$	30	-	-	V
$I_{DS(0)}$	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 24V, V_{GS} = 0V, T_J = 85^\circ\text{C}$	-	-	30	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$R_{DS(ON)}$	Static Drain-Source On-resistance <sup>*5</sup>	$V_{GS} = 10V, I_D = 6.3A$	-	-	30	$\text{m}\Omega$
		$V_{GS} = 4.5V, I_D = 4.8A$	-	-	45	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	-	2.5	V
<b>Dynamic Characteristics</b> <sup>*6</sup>						
$C_{ISS}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 15V$ $f = 1.0\text{MHz}$	-	515	-	pF
$C_{OSS}$	Output Capacitance		-	76	-	
$C_{RSS}$	Reverse Transfer Capacitance		-	65	-	
<b>Switching Characteristics</b> <sup>*6</sup>						
$t_{d(ON)}$	Turn-on Delay Time	$V_{GS} = 10V$ $V_{DD} = 15V$ $R_L = 2.6\Omega$ $R_G = 3\Omega$	-	4.5	-	ns
$t_r$	Turn-on Rise Time		-	2.4	-	
$t_{d(OFF)}$	Turn-Off Delay Time		-	14.8	-	
$t_f$	Turn-Off Fall Time		-	2.5	-	
$Q_G$	Total Gate-Charge	$V_{DD} = 15V$ $V_{GS} = 10V$ $I_D = 5.8A$	-	14.4	-	nC
$Q_{GS}$	Gate to Source Charge		-	2.4	-	
$Q_{GD}$	Gate to Drain (Miller) Charge		-	2.6	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage <sup>*5</sup>	$I_{SD} = 1A, V_{GS} = 0V, T_J = 25^\circ\text{C}$	-	-	1.1	V

Notes:

1. Pulse width limited by max. junction temperature
2.  $R_{\theta JA}$  steady state  $t=999\text{s}$ .  $R_{\theta JA}$  is measured with the device mounted on  $1\text{in}^2$ , FR-4 board with 2oz. Copper
3. The  $E_{AS}$  data shows Max. rating. The test condition is  $L = 0.5\text{mH}$
4.  $t < 10\text{s}$
5. Pulse test ; pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
6. Guaranteed by design, not subject to production testing

**Electrical Characteristics-TR2** (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-30	-	-	V
$I_{DS(0)}$	Zero Gate Voltage Drain Current	$V_{DS} = -24V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	-	-	-1	$\mu\text{A}$
		$V_{DS} = -24V, V_{GS} = 0V, T_J = 85^\circ\text{C}$	-	-	-30	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$R_{DS(ON)}$	Static Drain-Source On-resistance <sup>5</sup>	$V_{GS} = -10V, I_D = -4.1\text{A}$	-	40	46	$\text{m}\Omega$
		$V_{GS} = -4.5V, I_D = -3\text{A}$	-	55	65	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-	-2.5	V
<b>Dynamic Characteristics</b> <sup>6</sup>						
$C_{ISS}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = -15V$ $f = 1.0\text{MHz}$	-	565	-	pF
$C_{OSS}$	Output Capacitance		-	89	-	
$C_{RSS}$	Reverse Transfer Capacitance		-	77	-	
<b>Switching Characteristics</b>						
$Q_G$	Total Gate-Charge	$V_{DD} = -15V$ $V_{GS} = -4.5V$ $I_D = -4\text{A}$	-	7.2	-	nC
$Q_{GS}$	Gate to Source Charge		-	1.5	-	
$Q_{GD}$	Gate to Drain (Miller) Charge		-	2.8	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage <sup>5</sup>	$I_{SD} = -1\text{A}, V_{GS} = 0V, T_J = 25^\circ\text{C}$	-	-	-1	V

### Ratings and Characteristics Curves-TR1 (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

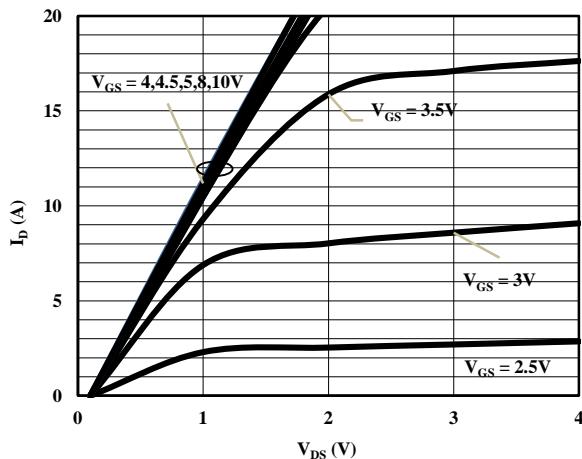


Fig 1 On-Region Characteristics

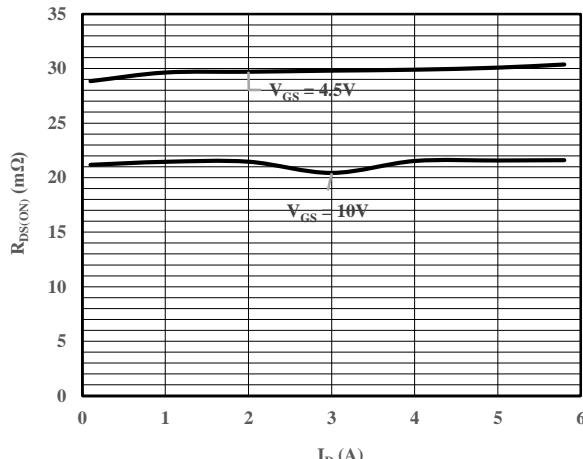


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

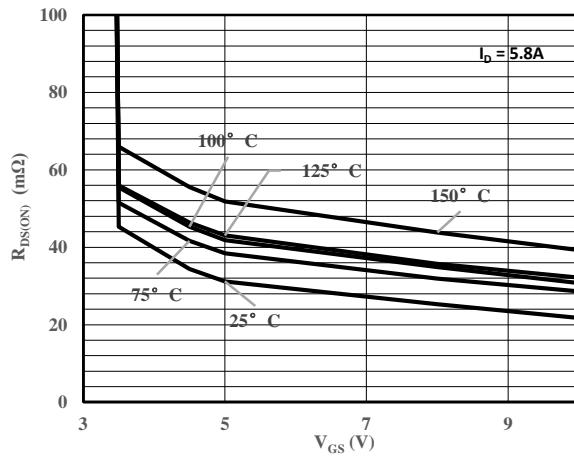


Fig 3 On-Resistance vs. Gate-Source Voltage

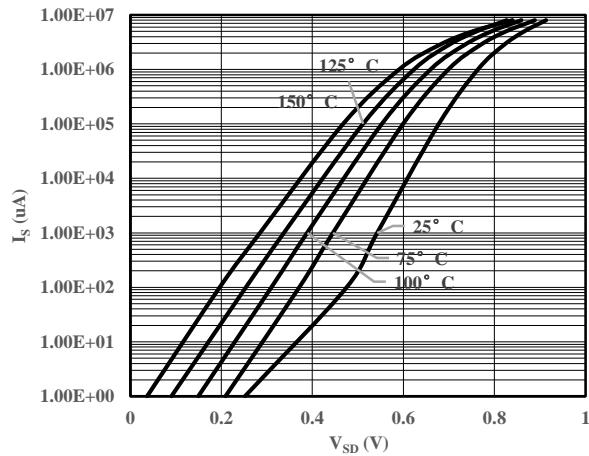


Fig 4 Body-Diode Characteristics

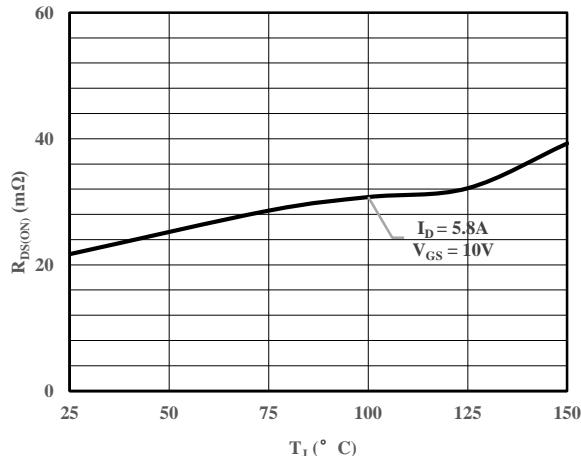


Fig 5 On-Resistance vs. Junction Temperature

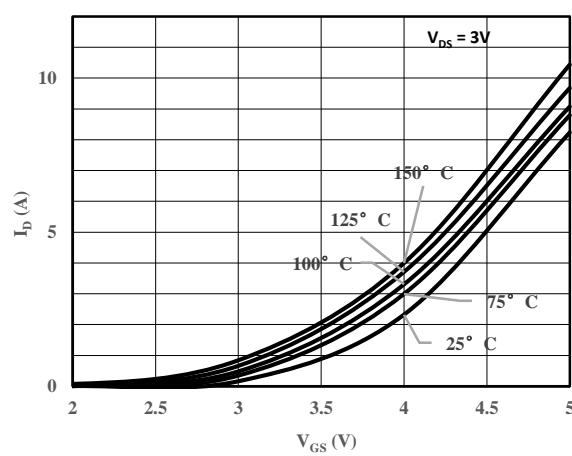


Fig 6 Transfer Characteristics

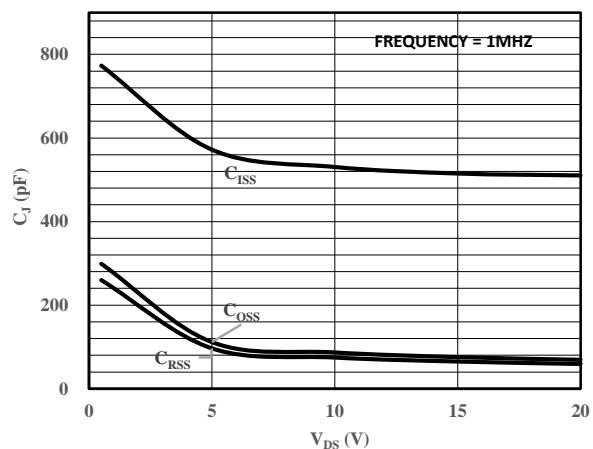


Fig 7 Capacitance Characteristics

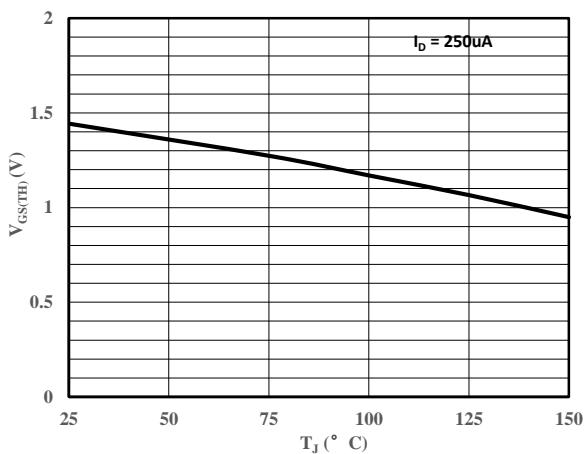


Fig 8 Gate Voltage vs. Junction Temperature

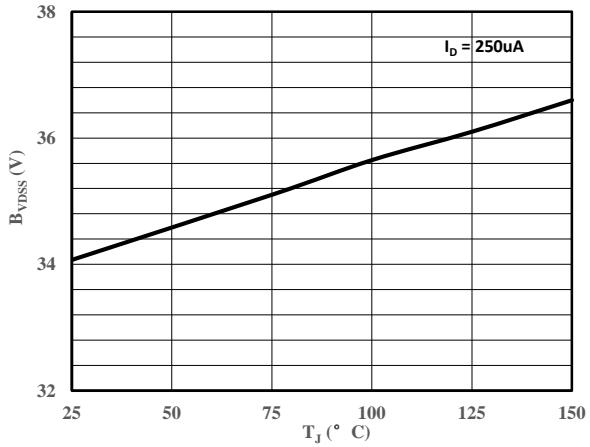


Fig 9 Drain-Source vs. Junction Temperature

### Ratings and Characteristics Curves-TR2 (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

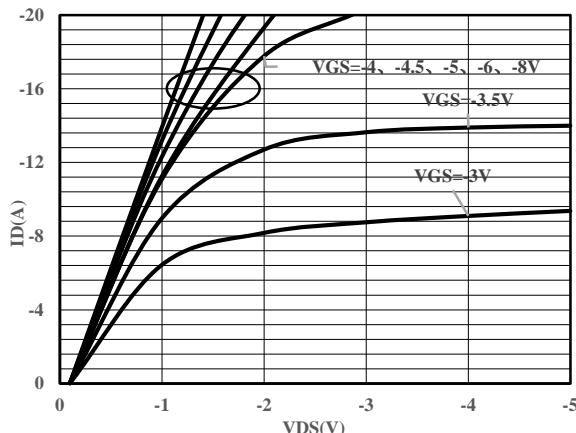


Fig.1- On-Region Characteristics

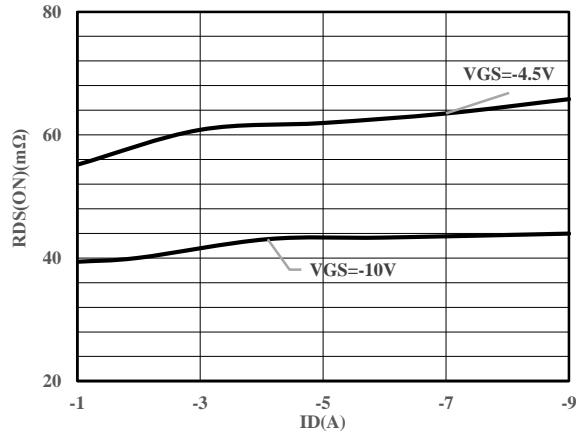


Fig.2- On-Resistance vs. Drain Current  
and Gate Voltage

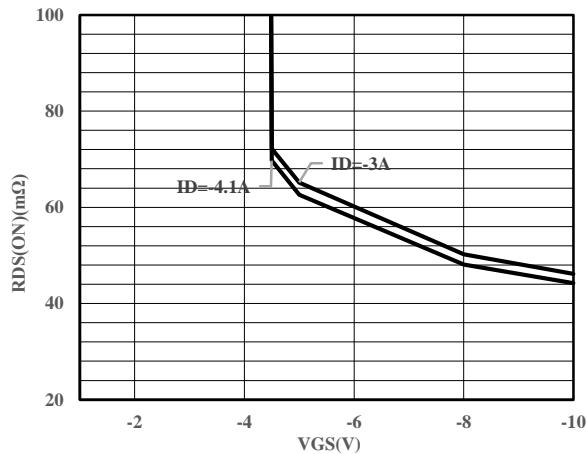


Fig.3- On-Resistance vs. Gate-Source Voltage

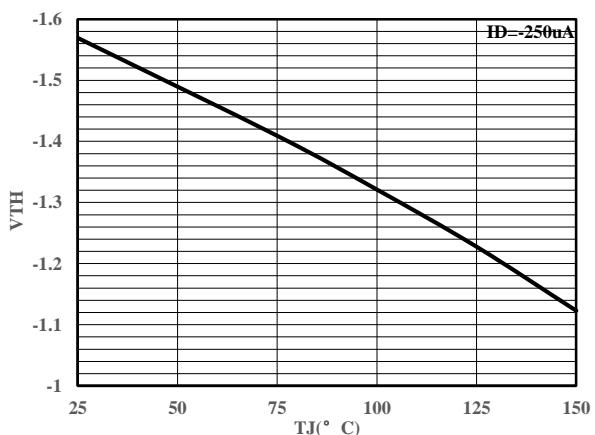


Fig.4- Gate Voltage vs. Junction Temperature

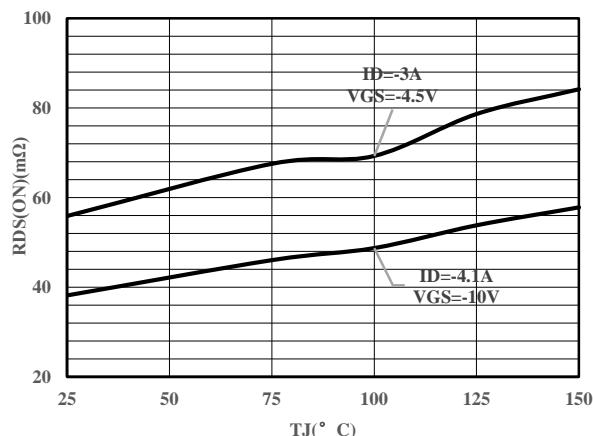


Fig.5- On-Resistance vs. Junction Temperature

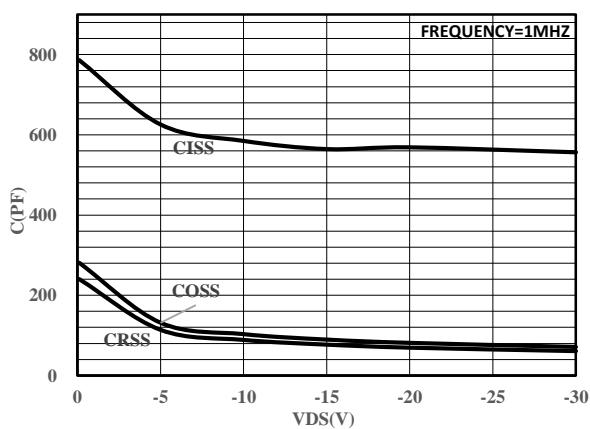
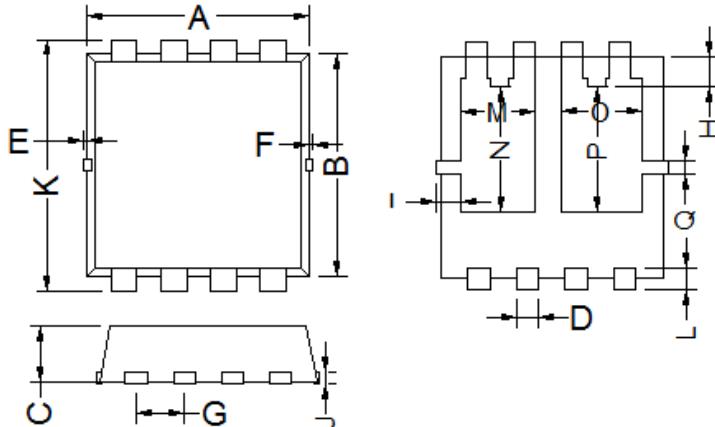


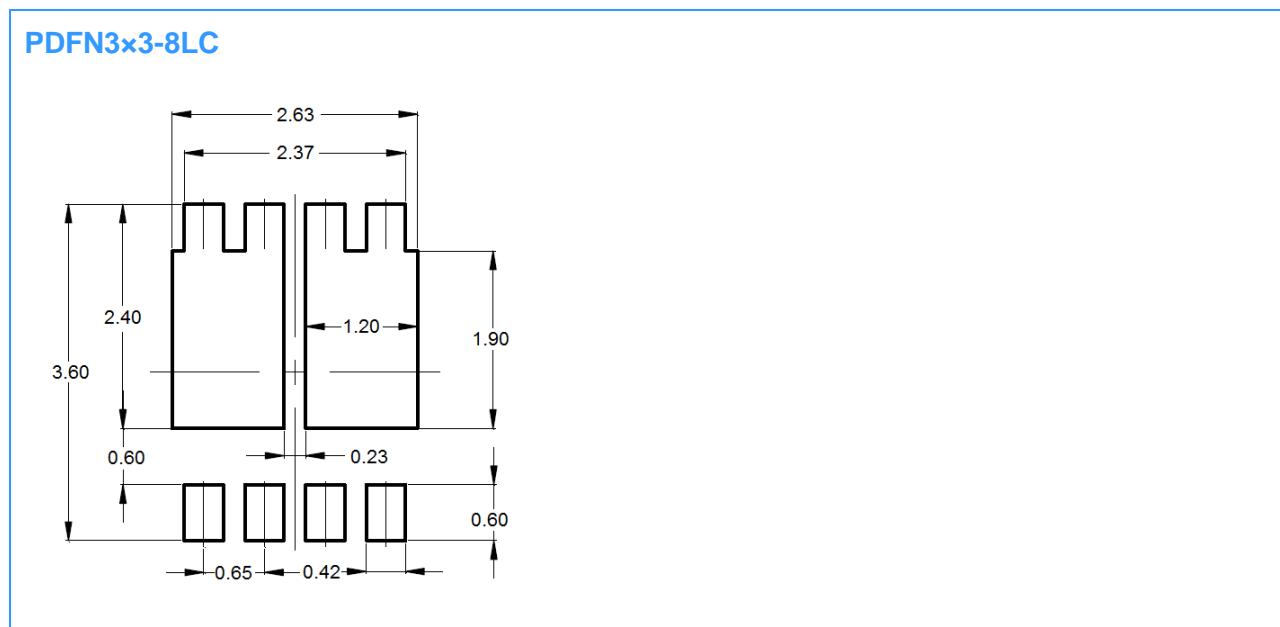
Fig.7- Capacitance Characteristics

### Package Outline Dimensions (Unit: mm)



PDFN3x3-8LC		
Dimension	Min.	Max.
A	2.90	3.10
B	2.90	3.10
C	0.55	0.75
D	0.20	0.40
E	0.00	0.20
F	0.00	0.20
G	0.55	0.75
H	0.20	0.40
I	0.20	0.40
J	0.10	0.20
K	3.15	3.45
L	0.25	0.45
M/O	0.90	1.20
N/P	1.65	1.85
Q	0.10	0.30

### Mounting Pad Layout (Unit: mm)



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